

SURFACE PREPARATION FOR RECEIVING
PROCESSING TREATMENTS

ABSTRACT

A solution for rinsing a surface that has been planarized using a chemical-mechanical planarization ("CMP") technique. The solution may be a surfactant solution introduced following the use of a polishing solution in the CMP technique. The surfactant solution acts to clear undesirable particles from the planarized surface and also can terminate "latent" effects from the polishing solution. A cleaning solution is generally injected after the rinsing solution for additional cleaning effects. A plate covered with a textured material such as a fabric is usually applied to the surface during the polishing, rinsing, or cleaning steps.